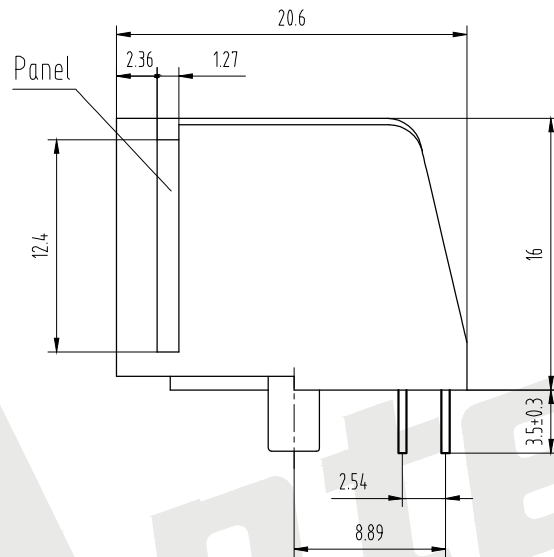
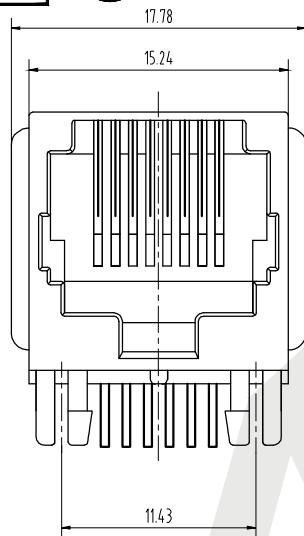


HSF

RoHS



NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE t=0.3mm
3. PLATING: SELECTING GOLD PLATING 1μ~50μ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD : 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING : 125VAC RMS
2. CURRENT RATING : 1.5AMP
3. CONTACT RESISTANCE : 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY : 750 CYCLES MIN
2. PCB RETENTION PRB-SOLDER : 1 LB MIN

REVISIONAL

1. STORAGE : -40° C TO 85° C
2. OPERATION : 0° C TO 70° C

Order code:

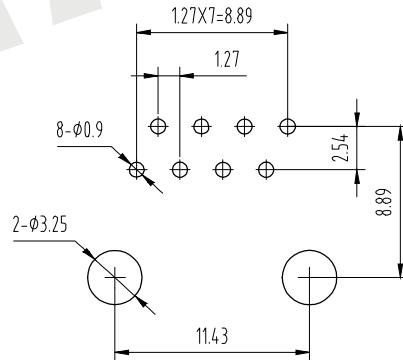
ATRJ5721 - 8P - 8C - X - A - X - A

① ② ③ ④ ⑤ ⑥ ⑦

- ① SERIES NO:
  - ② NUMBER OF POSITIONS (8P, 6P, 4P)
  - ③ NUMBER OF CONTACTS (8C, 6C, 4C)
  - ④ Contact Plating
  - ⑤ Shield
  - ⑥ Ports
  - ⑦ With Panel or not
- A: W/O Shield
  - B: Half Shield
  - C: Shield W/Eml
  - D: Shield W/O Eml
  - A: 1X1P
  - B: 1X2P
  - C: 1X4P
  - D: 1X5P
  - E: 1X6P
  - F: 1X8P
  - A: With panel
  - B: Without panel

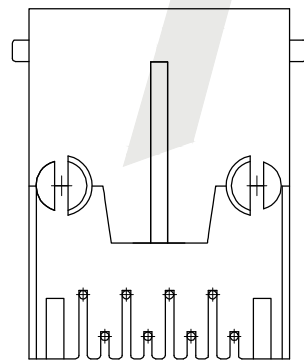
- G0: Gold flash
- G1: 3U" Gold
- G2: 5U" Gold
- G3: 10U" Gold
- G4: 15U" Gold
- G5: 30U" Gold
- SN: Tin

PCB LAYOUT



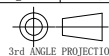
PC Board Layout

Component Side Shown



Unless Otherwise specified tolerance  
 X. ±0.35 X.XX: ±0.20  
 X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm  
 DRAW: Wu Feng Rong DATE: 22/03/2018  
 CHECK: BobYang DATE: 22/03/2018



ANTENK ELECTRONICS CO., LTD  
 Http://www.antenk.com  
 E-mail:sales@antenk.com

TITLE: Modular Jack Side entry 8P8C full Plastic with panel, Flat pin

DRAWING NO: ATRJ5721-8P8C-X-A-X-A

PRODUCT NO: ATRJ5721-8P8C-X-A-X-A

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		